Matthew A Ring

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/4323122/publications.pdf

Version: 2024-02-01

16	42	2258059 3	2550090 3
papers	citations	h-index	g-index

17	17	17	12
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Revealing stresses for plasma induced damage detection in thick oxides. , 2022, , .		0
2	Reliability Analysis of Storage Systems With Partially Repairable Devices. IEEE Transactions on Device and Materials Reliability, 2021, 21, 167-168.	2.0	0
3	Nano-CT imaging of electrically stressed power device metallization. , 2021, , .		0
4	Relation of PID well to gate antenna charging effects. , 2021, , .		6
5	BEOL Process Development Using Fast Power Cycling on Test Structures. , 2019, , .		1
6	Modeling Effect of Grain Orientation on Degradation in Tin-Based Solderâ€"Part II: Electromigration Experiments. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1993-1999.	2.5	3
7	Fast Power-Temperature Cycling of BEOL Test Structures for Power Devices. , 2018, , .		0
8	Multiple Modes of Electromigration Failure in SAC Solder Alloys. , 2018, , .		0
9	Integrated solder bump electromigration test chip and coupon cards for the characterization of Pb-free SAC solders under stress. , 2017, , .		0
10	Package reliability: How can we use ideas/methods from semiconductor reliability in package reliability?. , 2017, , .		0
11	Influences of the wafer-level testing method on unclamped inductive switching. , 2017, , .		0
12	Electromigration Induced Stress in Lead-Free Solder Joints. , 2016, , .		1
13	3D Power module with embedded WLCSP. , 2013, , .		7
14	Modeling for critical design and performance of wafer level chip scale package. , 2012, , .		12
15	Properties of a-Si:H and a-(Si,Ge):h films grown using combined hot wireâ€"ECR plasma processes. Journal of Non-Crystalline Solids, 2004, 338-340, 61-64.	3.1	5
16	Properties of a-Si:H films grown using hot wire-ECR plasma techniques. Thin Solid Films, 2003, 430, 91-94.	1.8	7